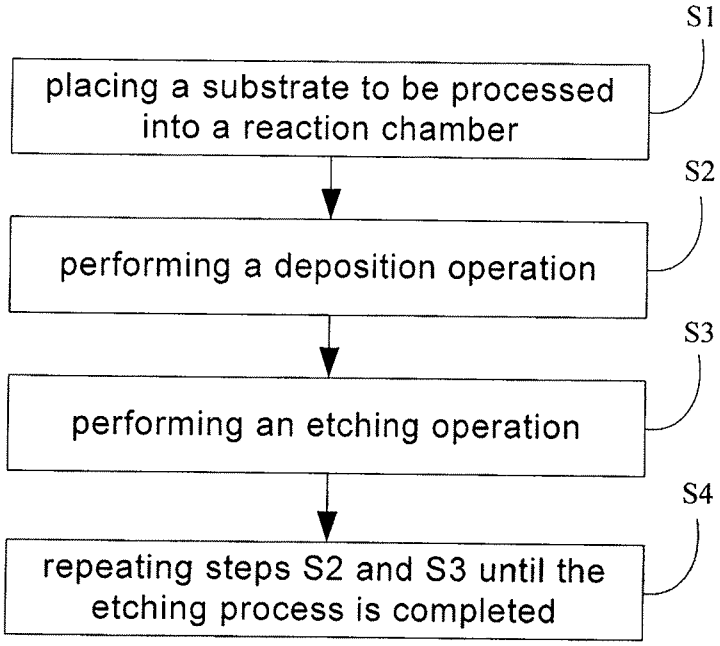

S1
placing a substrate to be processed into a reaction chamber
S2
performing a deposition operation
S3
performing an etching operation
S4
repeating steps S2 and S3 until the etching process is completed

FIG. 1

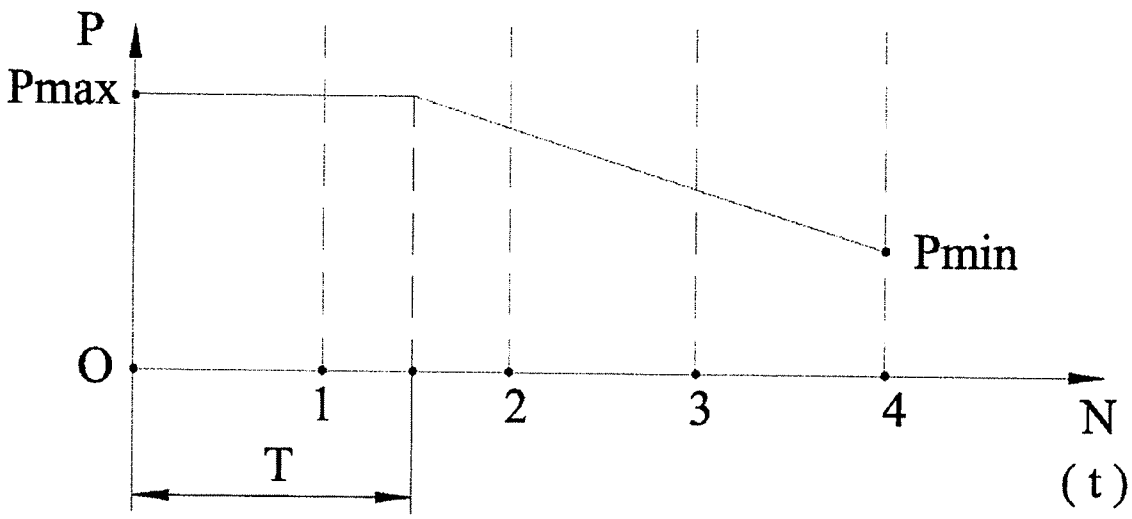

P
Pmax
Pmin
O
1
2
3
4
N
(t)
T

FIG. 2a

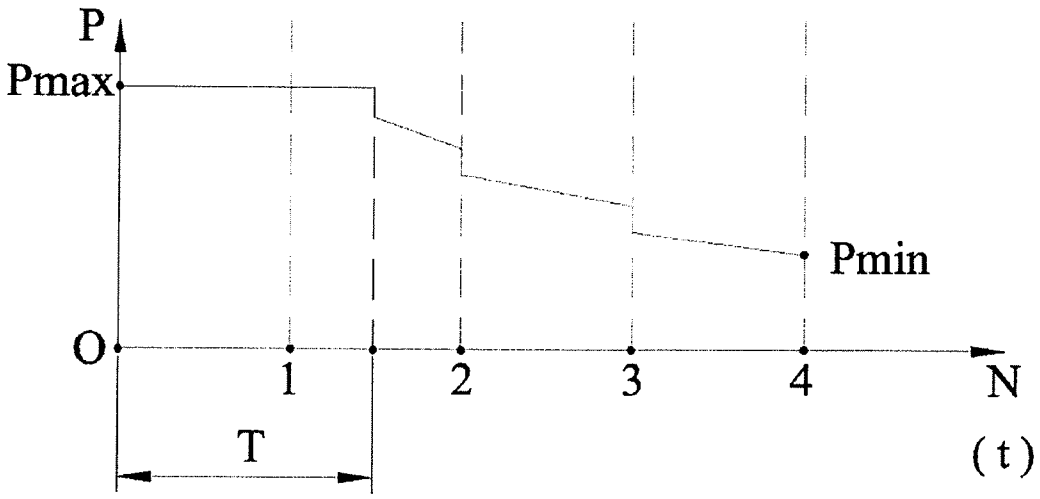


FIG. 2b

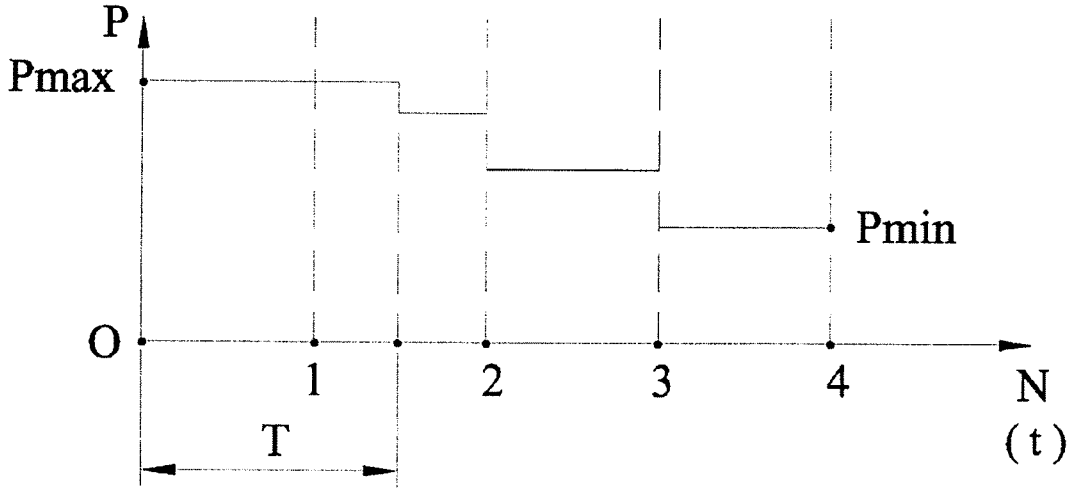


FIG. 2c

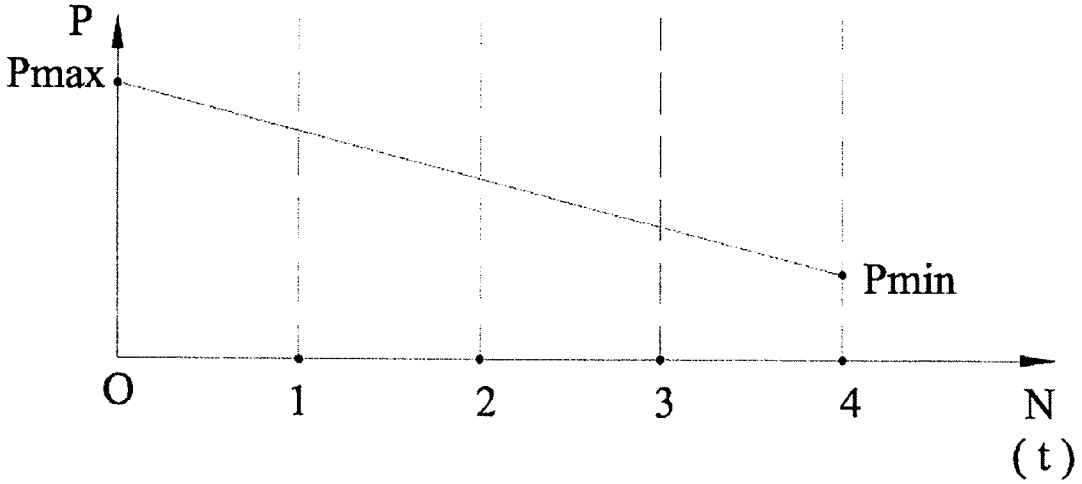


FIG. 2d

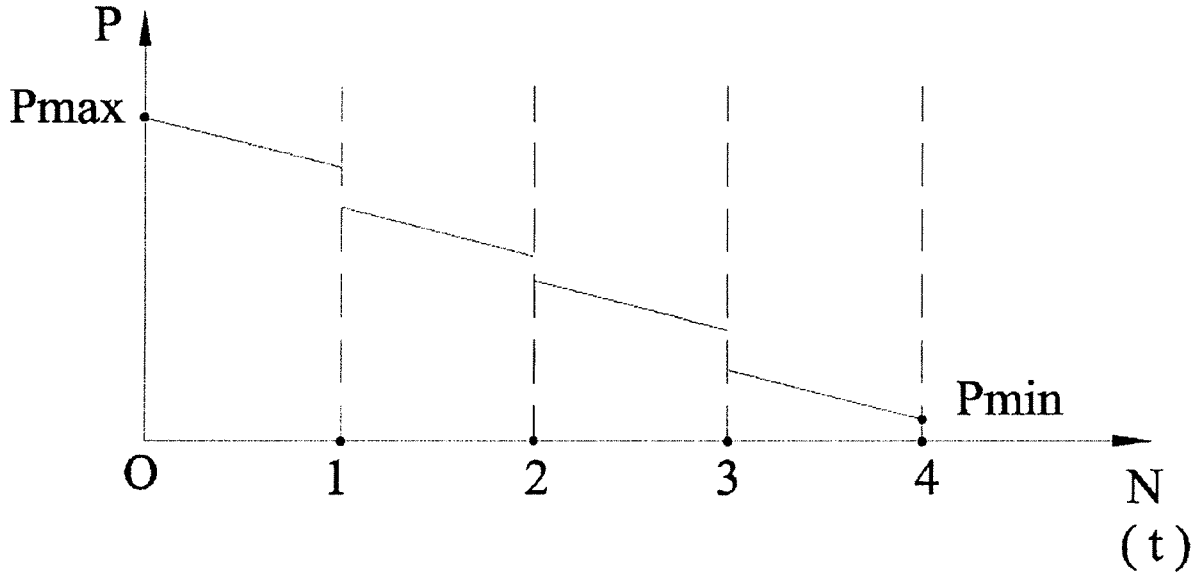


FIG. 2e

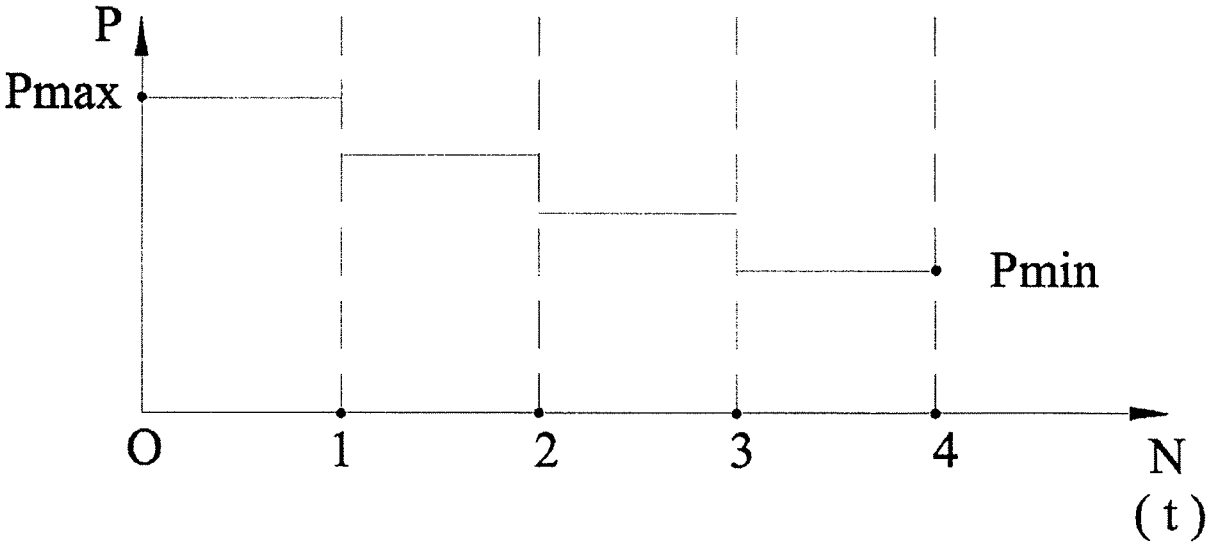


FIG. 2f

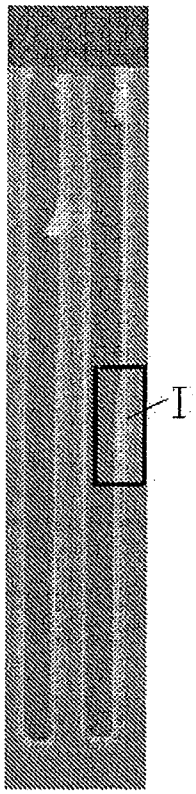


FIG. 3a

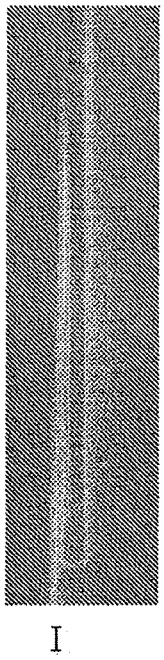


FIG. 3b

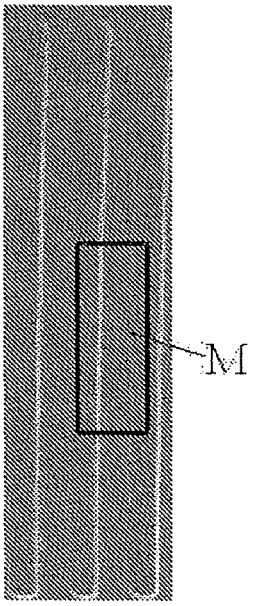


FIG. 3c

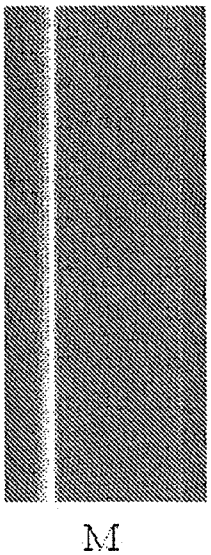


FIG. 3d